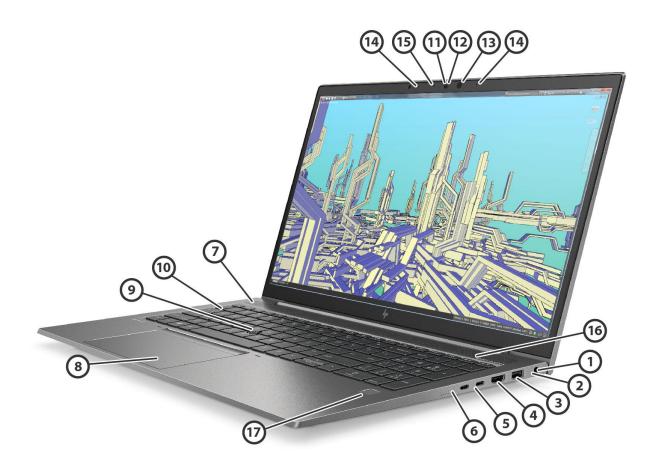
Overview

## **HP ZBook Firefly 15 G7 Mobile Workstation**



- 1. 4.5mm AC Power connector
- 2. Battery Charging LED
- 3. (1) USB 3.1 Gen 1 Type A
- 4. HDMI 2.0 (HDMI cable not included)
- 5. (2) USB Type-C<sup>®</sup> with Thunderbolt™ 3
- 6. Nano SIM card slot (optional)1
- 7 Speakers
- 8. Clickpad
- 9. Dual point stick with buttons
- 10. HP Premium Keyboard
- 11. HD Camera (select models only)

## Right

- 12. IR Camera (select models only)
- 13. HP Privacy Camera Shutter
- 14. Multi-array microphone
- 15. Webcam LED
- 16. Power button (on keyboard)
- 17. fingerprint sensor (optional)

<sup>1</sup>All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug

## Overview



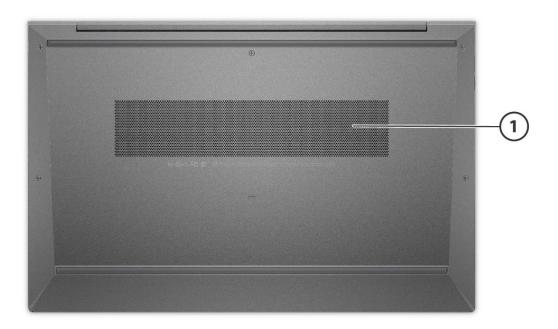
#### Left

- 1. Nano security lock slot (cable lock sold separately)
- 2. (1) USB 3.1 Gen 1 Type A charging port

- 3. Headphone/microphone combo jack
- 4. HP Smart Card Reader (optional)



Overview



## **Bottom**

## 1. Fan Venting

### Overview

### At A Glance

- Work anywhere without compromising on performance or security with Windows 10 Pro<sup>1</sup>, powered by HP's collaboration and connectivity technology.
- Open large files and run apps simultaneously for speedy multitasking and productivity with the NVIDIA® Quadro® P520 graphics with 4GB of video memory.
- Bring your ideas to life quickly and effectively with the 10th gen quad core Intel® Core™ processors² with up to 4.9 GHz of acceleration when you need it most.³
- Strenuously tested to meet ISV certification and deliver superb performance and support with leading software providers, including Autodesk and Adobe®.4
- Have confidence with the world's most secure mobile workstations. Instantly protect against visual hacking with HP Sure View Reflect and defend against firmware and malware attacks with HP Sure Start Gen 67 and HP Sure Sense 8.
- Built with the environment in mind, this ZBook includes recycled ocean-bound plastics<sup>10</sup>, plastic-free packaging, a reduction in hazardous material and ultra-efficient power consumption.
- The keyboard has been re-imagined with rubber domes, power button, and a quiet clickpad for a more comfortable, intuitive, and quiet experience. Easily input numbers with a dedicate number pad.
- Choice of modern viewing experiences:
  - o (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 400 nits, low power 100% sRGB
  - o (39.6 cm) 15.6" diagonal, 4K UHD (3840 x 2160), IPS, anti-glare, 400 nits, 100% sRGB
  - o (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 250 nits, 45% NTSC
  - (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 1000 nits, 72% NTSC, HP Sure View Reflect integrated
  - (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), touch, IPS, anti-glare, 250 nits, 45% NTSC
- Designed for ultimate durability, this ZBook undergoes brutal MIL-STD 810H <sup>11</sup> tests to help ensure this PC keeps rolling through your workday.
- Plug in to greater connectivity at your desktop with the HP Thunderbolt Dock (120W) for lightning-fast Thunderbolt™ 3<sup>12</sup> transfers and the flexibility to run up to two external 4K displays. <sup>13,14</sup>
- Work without limits in any location with up to 2TB<sup>15</sup> of local PCIe storage.
- 170 degree clamshell hinges lay almost flat, for easy collaboration and comfortable viewing at every angle.
- No need to risk riding someone else's network when you have your own. Optional 4G LTE<sup>16</sup> leverages the SIM card from your wireless provider for enhanced security.
- A completely revamped standby system means you're ready to work the moment inspiration strikes. With no sleep mode and no off mode, the modern standby keeps your rig connected and on demand whenever you need it.
- Improve connectivity while on Wi-Fi® with HP Extended Range Wireless LAN that allows greater distance from transmission point and fast data throughput at shorter ranges.<sup>17</sup>

<sup>1</sup>Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

<sup>2</sup>Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

<sup>3</sup>Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

<sup>4</sup>Adobe and Autodesk software sold separately.

<sup>5</sup>Based on HP's unique and comprehensive security capabilities at no additional cost among desktop workstation vendors as of Sept. 2017 on HP Mobile Workstations with 7th Gen and higher Intel® Processors.

<sup>6</sup>HP Sure View Reflect integrated privacy screen is an optional feature that must be configured at purchase.

<sup>7</sup>HP Sure Start Gen6 is available on select HP PCs with Intel processors. See product specifications for availability.

<sup>8</sup>HP Sure Sense requires Windows 10. See product specifications for availability.

<sup>&</sup>lt;sup>10</sup>Speaker enclosure component made with 5% ocean bound plastic as of 2/3/2020.



### Overview

<sup>11</sup>Testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

<sup>12</sup>HP Thunderbolt Dock with Thunderbolt<sup>™</sup> 3 sold separately.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



<sup>&</sup>lt;sup>13</sup>External displays sold separately.

<sup>&</sup>lt;sup>14</sup>Optional hybrid graphics is required to run up to two external 4K displays.

<sup>&</sup>lt;sup>15</sup>For hard drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30GB (for Windows 10) of system disk is reserved for system recovery software.

<sup>&</sup>lt;sup>16</sup>4G LTE is an optional feature, requires separately purchased service contract, and configuration at purchase. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

<sup>&</sup>lt;sup>17</sup>Based on internal testing vs. previous generation product with 802.11ac wireless LAN module.

#### **Features**

### **OPERATING SYSTEM**

Preinstalled OS Windows 10 Pro 64 - HP recommends Windows 10 Pro for business.<sup>1</sup>

Windows 10 Home 641

Windows 10 Home Single Language 641

Windows 10 Pro 64<sup>1</sup>

FreeDOS 3.0

**Web support OS** Windows 10 Enterprise 64<sup>1</sup>

**Supported Version** For testing information on newer versions of Windows 10, please see:

https://support.hp.com/document/c05195282.

<sup>1</sup> Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <a href="http://www.windows.com">http://www.windows.com</a>.

<sup>2</sup> Tested and documented only.

### **PROCESSOR**

10<sup>th</sup> Generation Intel® Core™ i7-10810U vPro™ with Intel® UHD Graphics (1.1 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 6 cores)<sup>1,2,3,4</sup>

10<sup>th</sup> Generation Intel® Core™ i7-10710U with Intel® UHD Graphics (1.1 GHz base frequency, up to 4.7 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 6 cores) <sup>1,2,3,4</sup>

10<sup>th</sup> Generation Intel® Core™ i7-10510U with Intel® UHD Graphics (1.8 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) <sup>1,2,3,4</sup>

10<sup>th</sup> Generation Intel® Core™ i7-10610U vPro™ with Intel® UHD Graphics (1.8 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)<sup>1,2,3,4</sup>

10<sup>th</sup> Generation Intel® Core™ i5-10310U vPro™ with Intel® UHD Graphics (1.7 GHz base frequency, up to 4.4 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores)<sup>1,2,3,4</sup>

10<sup>th</sup> Generation Intel® Core™ i5-10210U vPro™ with Intel® UHD Graphics (1.6 GHz base frequency, up to 4.2 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores) <sup>1,2,3,4</sup>

<sup>1</sup> Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

<sup>2</sup> Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

<sup>3</sup> Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

<sup>4</sup> In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.



**Features** 

### **CHIPSET**

Chipset is integrated with processor

## INTEL® CORE™ 15 WITH VPRO/CORE 17 WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™, Core™ i7 with vPro™ technology is a selectable feature that is available on units configured with select processors, a qualified Intel® WLAN module and a preinstalled Windows® operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off\* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state.

<sup>1</sup> Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

<sup>2</sup> Some functionality of Intel® Core™ i5 with vPro™/Core™ i7 with vPro™ technology, such as Intel® Active Management technology and Intel® Virtualization technology, requires additional third-party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro™/Core i7 with vPro™ technology is dependent on third-party software providers. Compatibility with future "virtual appliances" is yet to be determined.

## **GRAPHICS**

#### Integrated

Intel® UHD Graphics 1, 3, 5, 6

#### Discrete

NVIDIA® Quadro® P520 (4 GB GDDR5 dedicated)2,4

- <sup>2</sup> Both UMA & Discrete configurations support 3 independent displays when on the HP Thunderbolt Dock G2 (sold separately)
- Max. resolution = 2.5K @60Hz (DP1) & 2.5K @60Hz (DP2) & FHD (VGA) OR 4K @60Hz (one DP Port) & 4K @60Hz (Type-C output port using a Type C-to-DP adapter).
- <sup>3</sup> Support HD decode, DX12, HDMI 1.4, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4K @ 30Hz

### **DISPLAY**

### Non-touch

- (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 400 nits, low power 100% sRGB <sup>3,4</sup>
- (39.6 cm) 15.6" diagonal, 4K UHD (3840 x 2160), IPS, anti-glare, 400 nits, 100% sRGB<sup>2,3,4</sup>
- (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 250 nits, 45% NTSC<sup>3,4</sup>
- (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 1000 nits, 72% NTSC, HP Sure View Reflect integrated privacy screen 1,3,4,5

#### **Touch**



<sup>&</sup>lt;sup>1</sup> UHD content required to view UHD images.

<sup>&</sup>lt;sup>4</sup> HDMI cable Sold Separately

<sup>&</sup>lt;sup>5</sup> Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.

### **Features**

- (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), touch, IPS, anti-glare, 250 nits, 45% NTSC<sup>3,4,5</sup>
- <sup>1</sup> HP Sure View Reflect is optional and must be configured at purchase.
- <sup>2</sup> UHD content required to view UHD images.
- <sup>3</sup> Sold separately or as an optional feature.
- <sup>4</sup> Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- <sup>5</sup> Actual brightness will be lower with HP Sure View or touch screen.



#### **Features**

### STORAGE AND DRIVES\*

### PCIe® NVMe™ M.2 2280 Storage

256 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Self Encrypting (SED) Solid State Drive (SSD) 512 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Self Encrypting (SED) Solid State Drive (SSD) 256 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD) 512 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD) 1 TB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD) 2 TB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD) 2 TB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD) 256 GB PCIe® Gen3 x2 NVMe™ M.2 2280 TLC Value Solid State Drive (SSD) 128 GB PCIe® Gen3 x2 NVMe™ M.2 2280 TLC Solid State Drive (SSD)

### Intel® Optane™ Memory H10 with Solid State Storage

512 GB PCIe® Gen3 x4 NVMe™ M.2 2280 QLC Solid State Drive (SSD) + 32 GB Intel® Optane™ Memory¹

¹Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system.

\* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

### **DRIVE CONTROLLERS**

M.2 Storage Bay (PCIe NVMe) RAID:

PCIe Gen3 x4 lanes NVMe Solid State Drive Not supported

### **MEMORY**

#### **Maximum Memory**

64 GB DDR4-2666 non-ECC SDRAM 2 DDR4 SODIMMS Supports Dual Channel Memory<sup>1</sup> Slots are customer accessible / upgradeable

<sup>1</sup> Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.



#### **Features**

## **NETWORKING/COMMUNICATIONS**

#### **WLAN**

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, vPro<sup>™ 1</sup>
Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, non-vPro<sup>™ 1</sup>

<sup>1</sup>Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for Wi-Fi 6 (802.11ax WLAN) are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

#### WWAN1,2

Intel® XMM™ 7360 LTE Advanced CAT 9 Intel® XMM™ 7560 LTE-Advanced Pro Cat 16

<sup>1</sup> WWAN is an optional feature and requires factory configuration and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

<sup>2</sup> Gigabit class Category 16 4G LTE module is optional and must be configured at the factory. Module designed for up to 1 Gbps download speeds as carriers deploy 5 carrier aggregation and 100Mhz channel bandwidth, requires activation and separately purchased service contract. Backwards compatible to HSPA 3G technologies. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

**Optional Near Field Communication (NFC) module** 

## **AUDIO/MULTIMEDIA**

#### Audio

Audio by Bang & Olufsen, dual stereo speakers, HP World Facing Microphone multi-array digital microphone, functions keys for volume up and down, combo microphone/headphone jack, HD audio.

### Camera<sup>1, 2</sup>

720p HD webcam with IR 720p HD webcam



<sup>&</sup>lt;sup>1</sup> HD content required to view HD images.

<sup>&</sup>lt;sup>2</sup> Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.

#### **Features**

## **KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS**

#### **Keyboard**

HP Premium Quiet Keyboard, full-size with NumPad, spill-resistant, backlit, with DuraKeys, clickpad with image sensor and glass surface, multi-touch gestures and taps enabled

HP Premium Quiet Keyboard, full-size with NumPad, spill-resistant, with DuraKeys, clickpad with image sensor and glass surface, multi-touch gestures and taps enabled

#### **Pointing Devices**

Dual pointstick; Clickpad with multi-touch gestures enabled, taps enabled as default; Microsoft Precision Touchpad Default Gestures Support

### **SOFTWARE AND SECURITY**

#### Software

Bing search for IE11

**Buy Office** 

**HP Hotkey Support** 

**HP Noise Cancellation Software** 

HP Performance Advisor (download only)9

**HP Recovery Manager** 

HP ZCentral Remote Boost Software (download only)<sup>2</sup>

HP Support Assistant 1

Native Miracast support 5

HP Connection Optimizer<sup>10</sup>

**HP PC Hardware Diagnostics UEFI** 

**HP PC Hardware Diagnostics Windows** 

**HP Privacy Settings** 

**HP Touchpoint Customizer** 

**HP WorkWell** 

myHP

#### **Security Management**

Absolute persistence module 6

**HP Device Access Manager** 

**HP FingerPrint Sensor** 

HP Manageability Integration Kit Gen6 11

**HP Power On Authentication** 

HP Support Assistant<sup>7</sup>

Nano Security lock slot12

Trusted Platform Module TPM 2.0 Embedded Security Chip

Master Boot Record security

Pre-boot authentication

Microsoft Defender<sup>10</sup>

HP Client Security Manager Gen57, 17

HP BIOSphere Gen6 5

HP Sure Recover Gen3<sup>13</sup>

HP Sure Recover with Embedded Reimaging Gen3<sup>14</sup>

HP Sure Start Gen6 5, 15

HP Secure Erase 16

HP Sure Sense<sup>18</sup>

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

<sup>&</sup>lt;sup>2</sup> HP Z Central Remote Boost Software - The remote desktop solution for serious workstation users and their most demanding applications. Download at: http://www.hp.com/go/RGS.



<sup>&</sup>lt;sup>1</sup> HP Support Assistant - Requires Windows and Internet Access.

#### **Features**

- <sup>3</sup> HP Mobile Connect Pro is only available on preconfigured devices with WWAN. For geographic availability refer to http://www.hp.com/go/mobileconnect.
- <sup>4</sup> Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast.
- <sup>5</sup> HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations. HP Sure Start Gen5 Available on HP Elite and HP Z Workstation products equipped with Intel® 8th generation processors.
- <sup>6</sup> Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:
- http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- <sup>7</sup> Requires Windows and Intel<sup>®</sup> 8th generation processors.
- <sup>8</sup> HP Performance Advisor Software HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: https://www8.hp.com/us/en/workstations/performance-advisor.html <sup>9</sup> HP Connection Optimizer requires Windows 10.
- <sup>10</sup> Microsoft Defender Opt in and internet connection required for updates.
- <sup>11</sup> HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- <sup>12</sup> Security lock slot is Lock sold separately.
- <sup>13</sup> HP Sure Recover Gen3: See product specifications for availability. Requires an open, wired network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.
- <sup>14</sup> HP Sure Recover with Embedded Reimaging Gen3 is an optional feature which must be configured at purchase. See product specifications for availability. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before use to avoid loss of data.
- <sup>15</sup> HP Sure Start Gen6 is available on select HP PCs with Intel processors. See product specifications for availability.
- <sup>16</sup> For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- <sup>17</sup> HP Client Security Manager Gen6 requires Windows and is available on select HP Pro, Elite and ZBook PCs. See product specifications for details.
- <sup>18</sup> HP Sure Sense requires Windows 10. See product specifications for availability.
- <sup>19</sup> Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.



#### **Features**

### **POWER**

#### **Power Supply**

Up to 23 hours1

HP Long Life 3-cell, 56 Wh Li-ion polymer<sup>2</sup>

HP Smart 65 W External AC Power Adapter<sup>3</sup> HP Smart 45 W External AC Power Adapter

Supports battery fast charge: approximately 50% in 30 minutes (defined under system hibernation and off mode)

### **ENVIRONMENTAL**

Targeting ENERGY STAR® certified and EPEAT® GOLD registered configurations available <sup>1</sup> Low halogen<sup>2</sup>



<sup>&</sup>lt;sup>1</sup> Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark14 battery benchmark https://bapco.com/products/mobilemark-2014/ for additional details.

<sup>&</sup>lt;sup>2</sup> Supports HP Fast Charge Technology

<sup>&</sup>lt;sup>3</sup>45W Power Adapter is not available with Discrete Graphics Configurations.

<sup>&</sup>lt;sup>1</sup> Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

<sup>&</sup>lt;sup>2</sup> External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

#### **Features**

### **WEIGHTS & DIMENSIONS**

**Dimensions (w x d x h)** 35.95 x 23.36 x 1.92 cm 14.15 x 9.19 x 0.76 in

#### Weights

Starting at 1.7kg (3.74 lb)
Weight varies by configuration and components.

### PORTS/SLOTS

#### Left side

- 1 headphone/microphone combo
- 1 SuperSpeed USB Type-A 5Gbps signaling rate (charging) [USB 3.1 Gen 1 Type A charging]
- 1 SIM Card Slot (optional)

#### Right side

- 1 4.5mm AC power connector
- 1 SuperSpeed USB Type-A 5Gbps signaling rate [USB 3.1 Gen 1 Type A]
- 1 HDMI 2.0b
- 2 Thunderbolt<sup>™</sup> 3 (40Gbps signaling rate) with SuperSpeed USB Type-C<sup>®</sup> 10Gbps signaling rate (USB Power Delivery, DisplayPort<sup>™</sup> 1.2, HP Sleep and Charge) [USB Type-C<sup>®</sup> with Thunderbolt<sup>™</sup> 3] 1 Nano SIM Card Slot (optional)

#### SERVICE AND SUPPORT

3-year limited warranty options available, depending on country. Batteries have a default one-year limited warranty except for Long Life Batteries which will have same 1-year or 3-year limited warranty as the platform. Optional HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http://www.hp.com/go/cpc.

<sup>1</sup>Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.



## Technical Specifications – System Unit

### **SYSTEM UNIT**

Stand-Alone Power Nominal Operating

Requirements (AC Power) Voltage

19.5V

**Average Operating** 

Power(idle)

**WIN10** System in idle mo

System in idle mode + max Adapter Safety test panel brightness condition

250nit, 400nits, 550nits

**Integrated graphics** 6.78W **Discrete Graphics** 15.3W

Max Operating Power Discrete < 65W

**UMA < 45W** 

**Temperature Operating** 32° to 95° F (0° to 35° C) (not writing optical)

**Non-operating** 41° to 95° F (5° to 35° C) (writing optical)

**Relative Humidity** Operating 10% to 90%, non-condensing

**Non-operating** 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

-50 to 10,000 ft. (-15.24 to 3,048 m)

**Shock Operating** 40 G, 2 ms, half-sine

**Non-operating** 200 G, 2 ms, half-sine

**Random Vibration Operating** 0.75 grms

**Operating** 

Non-operating 1.50 grms

Maximum Altitude (unpressurized)

**Planned Industry** 

Certifications

**Standard** 

Non-operating -50 to 15,000 ft. (-15.24 to 12,192 m)
UL Yes
CSA Yes

**CSA** Yes **FCC Compliance** Yes

**ENERGY STAR®** Select models<sup>1</sup>

**EPEAT®** Registered Gold in United States **ICES** Yes

ICES Australia / NZ A-Tick

Compliance

Yes

CCC Yes
Japan VCCI Compliance Yes
KCC Yes
BSMI Yes
CE Marking Compliance Yes

MIL STD 810H Yes, passed 19 tests

BNCI or BELUS Yes
CIT Yes
GOST Yes

Saudi Arabian

Compliance (ICCP) Yes SABS Yes

<sup>1</sup>Configurations of the HP ZBook Firefly 15 G7 that are ENERGY STAR® qualified are identified as HP ZBook Firefly 15 G7 ENERGY STAR on HP websites and on http://www.energystar.gov.

## Technical Specifications – Displays

### **DISPLAYS**

15.6" diagonal, FHD (1920 x 1080), IPS, antiglare, 250 nits, 45% NTSC 
 Outline Dimensions (W x H)
 350.96 x 205.54 mm (max)

 Active Area
 344.16 x 193.59 mm (typ.)

Weight 370 g (max)
Diagonal Size 15.6 inch

Thickness 3.0 mm/ 5.0 mm (w/PCB) (max)

InterfaceeDP 1.2 (2 lane)Surface TreatmentAnti-Glare

Touch enabled No

Contrast Ratio600:1 (typ.)Refresh Rate60 HzBrightness250 nits

Pixel Resolution Pitch 1920 x 1080 (FHD)

Format RGB Stripe

Backlight LED

**Color Gamut Coverage** NTSC 45%

**Color Depth** 6 bits (Hi FRC supportive w/ condition to enable)

Viewing Angle UWVA 85/85/85

15.6" diagonal, FHD (1920 x 1080), touch, IPS, anti-glare, 250 nits, 45% NTSC **Outline Dimensions** (W x H) 350.96 x 205.74 mm (max) **Active Area** 344.16 x 193.59 mm (typ.)

Weight 380 g (max)
Diagonal Size 15.6 inch

Thickness 3.2mm/ 5.2mm (PCB) (max)

Interface eDP 1.2

**Surface Treatment** Anti-Glare On-cell touch

Touch enabledYESContrast Ratio600:1 (typ.)Refresh Rate60 HzBrightness250 nits

Pixel Resolution Pitch 1920 x 1080 (FHD)

Format RGB Stripe

BacklightLEDColor Gamut CoverageNTSC 45%Color Depth6 bits

Viewing Angle UWVA 85/85/85



### Technical Specifications – Displays

15.6" diagonal, FHD (1920 x 1080), IPS, antiglare, 400 nits, low power 100% sRGB **Outline Dimensions** (W x H) 349.46 x 204.79 mm (max) **Active Area** 344.16 x 193.59 mm (typ.)

Weight 325 g (max)
Diagonal Size 15.6 inch

Thickness 2.6mm / 4.6mm (PCB) (max)

InterfaceeDP 1.4Surface TreatmentAnti-Glare

Touch enabled No

Contrast Ratio 1200:1 (typ.)

**Refresh Rate** 60 Hz **Brightness** 400 nits

Pixel Resolution Pitch 1920 x 1080 (FHD)

Format RGB Stripe

Backlight LED

Color Gamut Coverage sRGB 100% (NTSC 72%)

Color Depth 8 bit

Viewing Angle UWVA 85/85/85

15.6" diagonal, 4K UHD (3840 x 2160), IPS, antiglare, 400 nits, low power 100% sRGB Outline Dimensions (W x H) 349.52 x 205.42 mm (max)

**Active Area** 344.22 x 193.62 mm (typ.)

Weight 320 g (max)
Diagonal Size 15.6 inch

Thickness 2.6mm / 4.6mm (PCB) (max)

InterfaceeDP 1.4Surface TreatmentAnti-Glare

Touch Enabled No

Contrast Ratio 1200:1 (typ.)

**Refresh Rate** 60 Hz **Brightness** 400 nits

Pixel Resolution Pitch 3840 x 2160 (UHD)

Format RGB Stripe

Backlight LED

**Color Gamut Coverage** sRGB 100% only for UHD LP

Color Depth 8 bit

Viewing Angle UWVA 85/85/85

15.6" diagonal, FHD (1920 x 1080), IPS, antiglare, 1000 nits, 72%

Outline Dimensions (W x H) 349.52 x 205.39 mm (max)

**Active Area** 344.16 x 193.59 mm (typ.)

## Technical Specifications – Displays

NTSC, HP Sure View Reflect integrated privacy screen Weight 370 g (max)
Diagonal Size 15.6 inch

Thickness 2.6mm / 4.6mm (PCB) (max)

Interface eDP 1.4 + PSR
Surface Treatment Anti-Glare (AG)

Touch Enabled No

Contrast Ratio1500:1 (typ)Refresh Rate60 HzBrightness1000 nits

Pixel Resolution Pitch 1920 x 1080 (FHD)

Format RGB

**Backlight** LED **PPI** 141

**Color Gamut Coverage** 100% sRGB

**Color Depth** 8 bit

Viewing Angle UWVA 85/85/85



### Technical Specifications – Storage

### STORAGE AND DRIVES

256 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD) Form Factor M.2 2280

Drive Weight 0.02 lb (10 g)

Capacity 256 GB

NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCle® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

2800 ~ 3500 MB/s 1400 ~ 2200 MB/s

**Logical Blocks** 500,118,192

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TRIM; L1.2

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

256 GB PCIe® Gen3 x2 NVMe™ M.2 2280 TLC Value Solid State Drive (SSD) 
 Form Factor
 M.2 2280

 Drive Weight
 0.02 lb (10 g)

 Capacity
 256 GB

 NAND Type
 Value TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCle® Gen3 x2 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

2100 ~ 2200 MB/s 900 ~ 1400 MB/s

**Logical Blocks** 500,118,192

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security (optional); TRIM; L1.2

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

256 GB PCIe® Gen3 x4 NVMe™ M.2 2280 QLC Solid State Drive (SSD) + 16 GB Intel® Optane™ Memory 
 Form Factor
 M.2 2280

 Drive Weight
 0.02 lb (10 g)

 Capacity
 256 GB + 16 GB

**Generation** H10

 NAND Type
 QLC + 3D XPoint

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCIe® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

Up to 1450 MB/s Up to 500 MB/s

**Logical Blocks** 500,118,192

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

### Technical Specifications – Storage

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

256 GB PCIe® Gen3 x4 Form Factor NVMe™ M.2 2280 TLC Self Drive Weight Encrypting (SED) Solid State Drive (SSD) Capacity

Form Factor M.2 2280

Drive Weight 0.02 lb (10 g)

Capacity 256 GB

NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCle® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

2800 ~ 3500 MB/s 1663 ~ 2200 MB/s

**Logical Blocks** 500,118,192

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

512 GB PCle® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD) Form Factor M.2 2280
Drive Weight 0.02 lb (10 g)
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCle® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

3100 ~ 3500 MB/s 2400 ~ 2956 MB/s

**Logical Blocks** 1,000,215,215

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TRIM; L1.2

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

512 GB PCIe® Gen3 x4 NVMe™ M.2 2280 QLC Solid State Drive (SSD) + 32 GB Intel® Optane™ Memory 
 Form Factor
 M.2 2280

 Drive Weight
 0.02 lb (10 g)

 Capacity
 512 GB + 32 GB

**Generation** H10

 NAND Type
 QLC + 3D XPoint

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCle® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

**Logical Blocks** 1,000,215,215

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]



### Technical Specifications – Storage

Features ATA Security; TRIM; L1.2

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

512 GB PCIe® Gen3 x4 Form Factor NVMe™ M.2 2280 TLC Self Drive Weight Encrypting (SED) Solid State Drive (SSD)

Form Factor M.2 2280
Drive Weight 0.02 lb (10 g)
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCIe® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

3100 ~ 3500 MB/s 2400 ~ 2956 MB/s

**Logical Blocks** 1,000,215,215

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

1 TB PCle® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD) 
 Form Factor
 M.2 2280

 Drive Weight
 0.02 lb (10 g)

**Capacity** 1 TB **NAND Type** TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCle® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

3100 ~ 3500 MB/s 2770 ~ 3037 MB/s

**Logical Blocks** 2,000,409,264

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TRIM; L1.2

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

2 TB PCle® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD) 
 Form Factor
 M.2 2280

 Drive Weight
 0.02 lb (10 g)

Capacity 2TB NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCIe® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

3180 ~ 3500 MB/s 2920 ~ 3000 MB/s

**Logical Blocks** 3,907,029,168

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]



Technical Specifications – Storage

**Features** 

ATA Security (Option); TRIM; L1.2

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.



Technical Specifications – Networking

## **NETWORKING/COMMUNICATION**

Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, nonvPro, supporting gigabit file transfer speeds) non-vPro

Wireless LAN Standards

IEEE 802.11a IEEE 802.11b IEEE 802.11a IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d

IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r

IEEE 802.11v

Interoperability **Frequency Band** 

Wi-Fi certified 802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan)

• 5.15 - 5.25 GHz • 5.25 - 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz

**Data Rates** 

• 802.11b: 1, 2, 5.5, 11 Mbps

• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz

& 160MHz)

Modulation

Security<sup>1</sup>

**Direct Sequence Spread Spectrum** 

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g

mode only

AES-CCMP: 128 bit in hardware

802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

 WPA2 certification • IEEE 802.11i

WAPI

**Network Architecture** 

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming **Output Power<sup>2</sup>**  IEEE 802.11 compliant roaming between access points

• 802.11b: +18.5dBm minimum

• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum

• 802.11n HT20(2.4GHz): +15.5dBm minimum

• 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum



## Technical Specifications – Networking

 802.11n HT40(5GHz): +14.5dBm minimum 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum • 802.11ax HT40(2.4GHz): +10dBm minimum • 802.11ax VHT160(5GHz): +10dBm minimum

**Power Consumption** Transmit mode 2.0 W

Receive mode 1.6 W

 Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mW

• Radio disabled 8 mW

ACPI and PCI Express compliant power management **Power Management** 

802.11 compliant power saving mode

Receiver Sensitivity<sup>3</sup> •802.11b, 1Mbps: -93.5dBm maximum

•802.11b, 11Mbps: -84dBm maximum • 802.11a/q, 6Mbps: -86dBm maximum • 802.11a/q, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum •802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

**Antenna Type** High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

**Form Factor** PCI-Express M.2 MiniCard with CNVi Interface

**Dimensions** 1. Type 2230 : 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

1. Type 2230: 2.8g Weight

2. Type 126: 1.3q

**Operating Voltage** 3.3v +/- 9%

**Temperature** Operating 14° to 158° F (-10° to 70° C)

> Non-operating -40° to 176° F (-40° to 80° C)

**Humidity** Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

**Altitude** Operating Non-0 to 10.000 ft (3.048 m)

operating 0 to 50,000 ft (15,240 m)

**LED Activity** LED Amber - Radio Off: LED Off - Radio ON HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Frequency Band 2402 to 2480 MHz

**Number of Available Channels** Legacy: 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

**Data Rates and Throughput** Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels



## Technical Specifications – Networking

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1

kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of + 9.5 dBm for BR and

EDR.

**Power Consumption** Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

**Bluetooth Software Supported** 

**Link Topology** 

Microsoft Windows Bluetooth Software

**Power Management** Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

**Power Management** ETS 300 328, ETS 300 826 **Certifications** Low Voltage Directive IEC950

UL, CSA, and CE Mark

**Bluetooth Profiles Supported** BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy

LE Privacy 1.2 -Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, vPro, supporting gigabit file transfer speeds)

vPro

Wireless LAN Standards IEEE 802.11a

IEEE 802.11b IEEE 802.11g

IEEE 802.11n

IEEE 802.11ac

IEEE 802.11ax IEEE 802.11d

IEEE 802.11e

IEEE 802.11h IEEE 802.11i

IEEE 802.11k IEEE 802.11r

IEEE 802.11v

Interoperability Wi-Fi certified Frequency Band 802.11b/g/n/ax

• 2.402 – 2.482 GHz 802.11a/n/ac/ax

4.9 – 4.95 GHz (Japan)



## Technical Specifications – Networking

tions – Networking	
	<ul> <li>5.15 – 5.25 GHz</li> <li>5.25 – 5.35 GHz</li> <li>5.47 – 5.725 GHz</li> <li>5.825 – 5.850 GHz</li> </ul>
Data Rates	<ul> <li>802.11b: 1, 2, 5.5, 11 Mbps</li> <li>802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)</li> <li>802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &amp; 160MHz)</li> <li>802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz &amp; 160MHz)</li> </ul>
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM
Security <sup>1</sup>	<ul> <li>IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only</li> <li>AES-CCMP: 128 bit in hardware</li> <li>802.1x authentication</li> <li>WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.</li> <li>WPA2 certification</li> <li>IEEE 802.11i</li> <li>WAPI</li> </ul>
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power <sup>2</sup>	<ul> <li>802.11b: +18.5dBm minimum</li> <li>802.11g: +17.5dBm minimum</li> <li>802.11a: +18.5dBm minimum</li> <li>802.11n HT20(2.4GHz): +15.5dBm minimum</li> <li>802.11n HT40(2.4GHz): +14.5dBm minimum</li> <li>802.11n HT20(5GHz): +15.5dBm minimum</li> <li>802.11n HT40(5GHz): +14.5dBm minimum</li> <li>802.11ac VHT80(5GHz): +11.5dBm minimum</li> <li>802.11ac VHT160(5GHz): +11.5dBm minimum</li> <li>802.11ax HT40(2.4GHz): +10dBm minimum</li> <li>802.11ax VHT160(5GHz): +10dBm minimum</li> </ul>
Power Consumption	<ul> <li>Transmit mode: 2.0 W</li> <li>Receive mode: 1.6 W</li> <li>Idle mode (PSP) 180 mW (WLAN Associated)</li> <li>Idle mode: 50 mW (WLAN unassociated)</li> <li>Connected Standby/Modern Standby: 10mW</li> <li>Radio disabled: 8 mW</li> </ul>
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity <sup>3</sup>	•802.11b, 1Mbps: -93.5dBm maximum •802.11b, 11Mbps: -84dBm maximum •802.11a/g, 6Mbps: -86dBm maximum •802.11a/g, 54Mbps: -72dBm maximum •802.11n, MCS07: -67dBm maximum



802.11n, MCS15: -64dBm maximum
802.11ac, MCS0: -84dBm maximum
802.11ac, MCS9: -59dBm maximum

## Technical Specifications – Networking

Antenna Type

**Altitude** 

•802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

**Dimensions** 1. Type 2230 : 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

**Weight** 1. Type 2230 : 2.8g

2. Type 126: 1.3g

**Operating Voltage** 3.3v +/- 9%

**Temperature** Operating 14° to 158° F (-10° to 70° C)

Non-operating  $-40^{\circ}$  to  $176^{\circ}$  F (-40° to  $80^{\circ}$  C)

**Humidity**Operating 10% to 90% (non-condensing)
Non-operating 5% to 95% (non-condensing)

Operating Non- 0 to 10,000 ft (3,048 m)

operating 0 to 50,000 ft (15,240 m)

LED Activity

LED Amber - Radio OFF; LED White - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Frequency Band 2402 to 2480 MHz

**Number of Available Channels** Legacy: 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

**Data Rates and Throughput** Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of + 9.5 dBm for BR and

EDR.

**Power Consumption** Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

**Bluetooth Software Supported** 

Link Topology

Microsoft Windows Bluetooth Software

**Power Management** Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

**Power Management** ETS 300 328, ETS 300 826 **Certifications** Low Voltage Directive IEC950

UL, CSA, and CE Mark

**Bluetooth Profiles Supported** BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer



## Technical Specifications – Networking

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

**Security & Manageability** 

Intel® vPro™ support with appropriate Intel® chipset components

#### Intel® XMM™ 7360 LTE-Advanced CAT9\*

Technology/Operating

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

bands

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100

(Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol

standards

3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz

throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

**GPS** Standalone, A-GPS (MS-A, MS-B)

**GPS bands** 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power

LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 5.8 q

**Dimensions** 42 x 30

(Length x Width x

Thickness)

42 x 30 x 2.3 mm

\* Mobile Broadband is an optional feature and requires configuration at purchase. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

#### Intel® XMM™ 7560 LTE-Advanced Pro DL CAT16\*

**Technology/Operating** FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

bands 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13



## Technical Specifications – Networking

upper), 700 (Band 14 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30),

1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41), 3500 (Band 42), 5200

(Band 46 RX only)

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol standards

3GPP Release 12 LTE Specification DL-CAT.16, DL 100MHz BW throughput up to 978Mbps; UL-CAT.7

20MHz throughput up to 75Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

**GPS** Standalone, A-GPS (MS-A, MS-B)

**GPS Bands** 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz

Maximum Data Rates LTE: 978 Mbps (Download), 75 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

Maximum Output Power LTE: 23 dBm in all band except B41

LTE B41 HPUE = 26dBm HSPA+: 23.5 dBm

Maximum Power Consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 g

**Dimensions** 42 x 30 x 2.3 mm

(Length x Width x Thickness)

\* Mobile Broadband is an optional feature and requires configuration at purchase. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

### **Near Field Communications Controller (optional)**

Dimensions (L x W

**x H)** Module 25 mm by 10 mm by 2.0 mm

Chipset NPC100 System interface I2C

NFC RF standards ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

**NFC Forum Support** 

Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD)
Mode(1)

ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693

MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa

Jewel and Topaz cards



## Technical Specifications – Networking

Card Emulation (PICC- ISO/IEC 14443 A VICC) Mode(1) ISO/IEC 14443 B and B'

MIFARE FeliCa

Frequency 13.56 MHz

NFC Modes Supported Reader/Writer, Peer-to-Peer Raw RF Data Rates 106, 212, 424, 848 kbps

Operating

temperature 0°C to 70°C

Storage temperature -20°C to 125°C

Humidity 10-90% operating 5-95% non-operating

**Supply Operating** 

**voltage** 4.35 to 5.25 Volts **I/O Voltage** 1.8V or 3.3V

**Power Consumption** Booster enable, VBAT= 3.3V,

VCC\_BOOST = 5V)
Mode Power
Consumption,
Typical

Polling 7.3 mA

Detected Test Total 283.8 mA

Tag Type 1 Net Module 236.8 mA

Detected Test Total 288.8 mA

Net Module 241.8 mA

Detected Test Total 287.7 mA

Net Module 240.7 mA

Detected Test Total 282.3 mA

Tag Type 4 Net Module 235.3 mA

**Antenna** Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is

external to module.



## Technical Specifications – Power

### **POWER**

HP 45W Smart AC Adapter Dimensions 95x45x26.8mm (nPFC Standard Barrel 4.5mm Right Angle 1.8m unit: 200g +/- 10g

Input Input Efficiency 87.74 % at 115 Vac and 88.4 % at 230 Vac

**Input frequency** 47 ~ 63 Hz

range

Input AC current Max. 1.4 A at 90 Vac

Output Output power 45W

**DC output** 19.5V

**Hold-up time** 5ms at 115 Vac input

Output current limit <8.0A

**Connector** 4.5mm Barrel Type

**Environmental Design**Operating temperature
32° to 95° F (0° to 35° C)

Non-operating

(storage) -4° to 185° F (-20° to 85° C)

temperature

**Altitude** 0 to 16,400 ft (0 to 5,000 m)

**Humidity** 20% to 95% **Storage Humidity** 10% to 95%

**EMI and Safety Certifications** Eg:

\*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 200,000 hours at 25°C ambient condition.

HP 45W Smart AC Adapter Dimensions (nPFC Standard Barrel 4.5mm Right Angle 1.8m 2prong) Input

 Dimensions
 95x45x26.8mm

 Weight
 unit: 200g +/- 10g

Input Input Efficiency 87.74 % at 115 Vac and 88.4 % at 230 Vac

Input frequency

range

47 to 63 Hz

Input AC current Max. 1.4 A at 90 Vac

Output Output power 45W

**DC output** 19.5V

**Hold-up time** 5ms at 115 Vac input

Output current limit <8.0A

**Connector** 4.5mm Barrel Type

**Environmental Design** Operating 32° to 95° F (0° to 35° C)

temperature



## Technical Specifications – Power

Non-operating

-4° to 185° F (-20° to 85° C)

(storage) temperature

**Altitude** 0 to 16,400 ft (0 to 5000m)

**Humidity** 20% to 95% **Storage Humidity** 10% to 95%

**EMI and Safety Certifications** Eg:

\*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W Smart AC Adapter Dimensions

(nPFC Slim USB-C® Straight 1.8m)

Weight Input 88x53.5x21mm unit: 220g +/- 10g

Input Efficiency

81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

**Input frequency range** 47 ~ 63 Hz

Input AC current 1.6 A at 90 VAC and maximum load

Output Output power 65W

**DC output** 5V/9V/12V/15V/20V **Hold-up time** 5ms at 115 Vac input

Output current limit <8.0A

**Connector** USB Type C®

**Environmental Design** Operating 32° to 95° F (0° to 35° C)

temperature

**Non-operating (storage)** -4° to 185° F (-20° to 85° C)

temperature

**Altitude** 0 to 16,400 ft (0 to 5000m)

**Humidity** 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety E Certifications \*0

\*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC

Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 100,000 hours at 25°C ambient condition.



## Technical Specifications – Power

HP 65W Smart AC
<b>Adapter (nPFC Standard</b>
USB-C® Straight 1.8m)

Dimensions90.0x51x28.5mmWeightunit: 250g +/- 10gInputInput Efficiency

81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

**Input frequency range** 47 ~ 63 Hz

**Input AC current** 1.6 A at 90 VAC and maximum load

Output Output power 65W

**DC output** 5V/9V/12V/15V/20V **Hold-up time** 5ms at 115 Vac input

**Output current limit** 8.0A Max.

**Connector** USB TYPE C®

Environmental Design Operating temperature 32° to 95° F (0° to 35° C)

Non-operating (storage)

temperature

-4° to 185° F (-20° to 85° C)

**Altitude** 0 to 16,400 ft (0 to 5000m)

**Humidity** 20% to 95% **Storage Humidity** 10% to 95%

**EMI and Safety** Eg

**Certifications** "CE Mark - full compliance with LVD and EMC directives

\*Worldwide safety standards -IEC60950, EN60950, UL60950, UL62368, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022

Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. \*MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W Smart AC Adapter (nPFC Standard Barrel 4.5mm for Emerging Markets) 
 Dimensions
 102x55x30mm

 Weight
 unit: 250g +/- 10g

Input Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230 Vac

Input frequency

range

47 ~ 63 Hz

Input AC current Max. 1.7 A at 90 Vac

Output Output power 65W

**DC output** 19.5V

**Hold-up time** 5ms at 115 Vac input

Output current limit <11.0A

**Connector** 4.5mm Barrel Type

**Environmental Design Operating** 320F to 950F (0oto 350C)

temperature

**Non-operating** -4oF to 185oF (-20oto 85oC)

(storage) temperature

**Altitude** 0 to 16,400 ft (0 to 5,000 m)



## Technical Specifications – Power

**Humidity** 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety

**Certifications** \*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W Smart AC Adapter (nPFC Standard Barrel 4.5mm Right Angle 1.8m) **Dimensions** 90x51x28.5mm

**Weight** unit: 230g +/- 10g

Input Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230Vac

**Input frequency range** 47 ~ 63 Hz

Input AC current Max. 1.7 A at 90 Vac

Output Output power 65W

DC output 19.5V

**Hold-up time** 5ms at 115 Vac input

Output current limit <11.0A

**Connector** 4.5mm Barrel Type

Environmental Design Operating temperature 32° to 95° F (0° to 35° C)

Non-operating (storage)

temperature

-4° to 185° F (-20° to 85° C)

**Altitude** 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% Storage Humidity 10% to 95%

**EMI and Safety** Eg:

**Certifications** \*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 200,000 hours at 25°C ambient condition.

HP 3-cell Long Life Battery (56 WHr) supporting HP Fast Charge **Dimensions (H x W x L)** 7.0 x 66.5 x 276.3 mm (0.275 x 2.618 x 10.877 inch)

**Weight** 0.215kg (0.45 lb)

Cells/Type3cell Lithium-Ion Polymer cell / 615383EnergyVoltage11.55V

Amp-hour capacity 4.59Ah Watt-hour capacity 56Wh

**Temperature** Operating (Charging) 32° to 122° F (0° to 50° C)

Operating (Discharging) 14° to 140° F (-10° to 60° C)

Fuel Gauge LED NA

Warranty Depends on system offering

Technical Specifications – Power

**Optional Travel Battery** No **Available** 



### Technical Specifications – Environmental

#### **ENVIRONMENTAL DATA**

## Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country.

#### **System Configuration**

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

#### Energy Consumption (in accordance with US ENERGY STAR® test method)

115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
5.70 W	5.74 W	5.49 W	
2.99 W	2.43 W	2.31 W	
1.37 W	1.38 W	1.32 W	
0.35 W	0.52 W	0.35 W	
	5.70 W 2.99 W 1.37 W	5.70 W 5.74 W 2.99 W 2.43 W 1.37 W 1.38 W	

#### NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	12 BTU/hr	12 BTU/hr	12 BTU/hr
Normal Operation (Long idle)	6 BTU/hr	5 BTU/hr	5 BTU/hr
Sleep	3 BTU/hr	3 BTU/hr	3 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr

**\*NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

## Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

Typically Configured – Idle Fixed Disk – Random writes

### **Longevity and Upgrading**

Sound Power	Sound Pressure
(L <sub>WAd</sub> , bels)	(L <sub>pAm</sub> , decibels)
2.5	14
2.8	20

"This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- 3 USB ports
- 2 SODIMM memory slots
- Interchangeable HDD

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.



## Technical Specifications – Environmental

#### **Batteries**

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight

Battery description: CR2032 (coin cell)

Battery type: Lithium

#### **Additional Information**

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 7.8% post-consumer recycled plastic (by wt.)
- This product is 96.1% recycle-able when properly disposed of at end of life.

### **Packaging Materials**

External:	PAPER/Cardboard & misc	235 g
Internal:	PLASTIC/EPE (Expanded Polyethylene)	27 g
	PLASTIC/Polyethylene low density	13 g
	PLASTIC/Polypropylene	3 g

The plastic packaging material contains at least 50% recycled content.

The corrugated paper packaging materials contains at least 70% recycled content.

### **Material Usage**

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)



## Technical Specifications - Environmental

- Polyvinyl Chloride (PVC) except for wires and cables, has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

#### **Packaging Usage**

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

## End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <a href="http://www.hp.com/go/reuse-recycle">http://www.hp.com/go/reuse-recycle</a> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the HP web site at: <a href="http://www.hp.com/go/recyclers">http://www.hp.com/go/recyclers</a>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

## HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

**Global Citizenship Report** 

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

**Eco-label certifications** 

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Copyright © 2020 HP Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

Intel, Core, and Celeron, Thunderbolt and vPro are registered trademarks or trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries. Bluetooth is a registered trademark of its proprietor used by HP Inc. under license. AMD, FirePro, and Enduro are trademarks of Advanced Micro Devices, Inc. Adobe is a trademark of Adobe Systems Incorporated. Microsoft and Windows are U.S. registered trademarks of Microsoft Corporation in the United States and/or other countries. Qualcomm and Snapdragon are trademarks of Qualcomm, Inc. SD, SDHC, and SDXC are trademarks or registered trademarks of SD-3C in the United States, other countries or both. USB Type-C and USB-C are trademarks of USB Implementers Forum. ENERGY STAR® is a registered trademark mark of the U.S. Environmental Protection Agency.

Date of change:	Version History:		Description of change:
July 22, 2020	From v1 to v2	Changed	OPERATING SYSTEM, PROCESSOR, WEIGHTS & DIMENSIONS and ENVIRONMENTAL DATA sections
November 11, 2020	From v2 to v3	Changed	At A Glance, OPERATING SYSTEM, GRAPHICS, DISPLAY, STORAGE AND DRIVES, KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS, SOFTWARE AND SECURITY, PORTS/SLOTS sections

